

P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary (Typ @VGS = -4.5V, TA = +25°C)

BV _{DSS}	Rds(on)	lp		
201/	37mΩ @ V _{GS} = -4.5V	-4.6A		
-20V	49mΩ @ V _{GS} = -2.5V	-3.7A		

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Battery managements
- Load switches
- · Battery protections

Features and Benefits

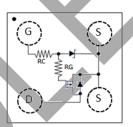
- Low Qg & Qgd
- Small Footprint
- Low Profile 0.62mm Height
- ESD Protected Up To 3KV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Package: U-WLB1010-4
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal: Finish SnAgCu. Solderable per MIL-STD-202 Method 208 ①
- Terminal Connections: See Diagram Below

U-WLB1010-4 (Type C)





Top View Equivalent Circuit

Ordering Information (Note 4)

Part Number	Package	Packing				
Part Number	Package	Qty.	Carrier			
DMP2042UCB4-7	U-WLB1010-4 (Type C)	3000	Tape & Reel			

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

2A YM 2A = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: J = 2022) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Year	2016		2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	D		J	K	L	М	N	0	Р	R	S	Т
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	VDSS	-20	V
Gate-Source Voltage	V _{GSS}	-6	V
Continuous Drain Current (Note 5) V _{GS} = -4.5V	ΙD	-4.6	Α
Continuous Drain Current (Note 5) V _{GS} = -2.5V	I _D	-3.7	Α
Pulsed Drain Current (Note 6)	I _{DM}	-16	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7)	PD	0.75	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 7)	$R_{\theta JA}$	165	°C/W
Power Dissipation (Note 5)	PD	1.4	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	Reja	87	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

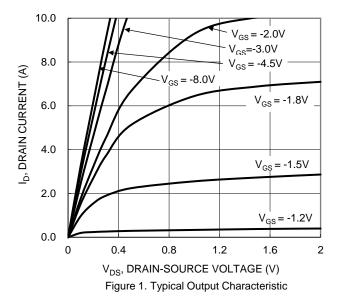
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BVDSS	-20		_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	1		-1	μΑ	V _{DS} = -16V, V _{GS} = 0V	
Gate-Source Leakage	Igss			-100	nA	$V_{GS} = -6V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	-0.4	-0.8	-1.2	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance	C	+	37	45	mΩ	V _G S = -4.5V, I _D =-1A	
Static Drain-Source On-Resistance	Rds(on)	7	49	65	11177	$V_{GS} = -2.5V, I_{D} = -1A$	
Forward Transfer Admittance	YFS	_	6.6	-	S	V _{DS} = -10V, I _D = -1A	
Diode Forward Voltage	VsD	_	-0.7	-1.0	V	V _G S = 0V, I _S = -1A	
DYNAMIC CHARACTERISTICS (Note 9)					•		
Input Capacitance	Ciss	_	218	_		V _{DS} = -10V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	148	_	pF		
Reverse Transfer Capacitance	Crss	_	11	_		1 = 1.01VII 12	
Series Gate Resistance	Rg	_	20	_	Ω	f 4MH= \/ 0\/ \/ 0\/	
Series Clamp Resistance	Rc	_	5,000	_	Ω	$f = 1MHz$, $V_{GS} = 0V$, $V_{DS} = 0V$	
Total Gate Charge	Qg	_	2.5	_			
Gate-Source Charge	Qgs	_	0.4	_		$V_{GS} = -4.5V, V_{DS} = -10V,$	
Gate-Drain Charge	Qgd	_	0.4	_	nC	I _D =-1A	
Gate Charge at VTH	Q _{g(TH)}	_	0.2	_			
Turn-On Delay Time	tD(ON)	_	0.6	_			
Turn-On Rise Time	tR	_	0.8	_		$V_{DS} = -10V, V_{GS} = -2.5V,$	
Turn-Off Delay Time	tD(OFF)	_	1.4	_	μs	$R_G = 10\Omega$, $I_D = -1A$	
Turn-Off Fall Time	tF	_	0.8	_			
Reverse Recovery Charge	Q _{RR}	_	2.2	_	nC	$V_{DD} = -10V$, $I_F = -1.0A$,	
Reverse Recovery Time	t _{RR}	_	10	_	ns	di/dt =100A/µs	

Notes:

- 5. Device mounted on FR-4 material with 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu.
- Device mounted on FR-4 material with 1-inch (0.49-cn)-1, 2-02. (0.071-inin thick) cu.
 Repetitive rating, pulse width limited by junction temperature.
 Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing.





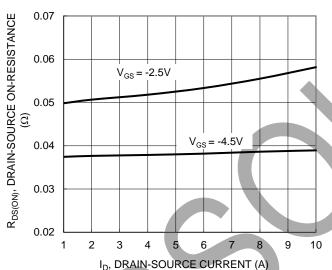


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

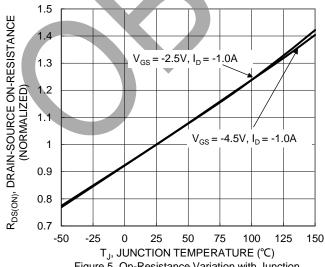
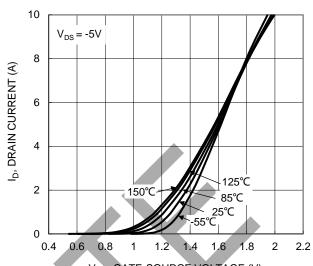


Figure 5. On-Resistance Variation with Junction Temperature



V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 2. Typical Transfer Characteristic

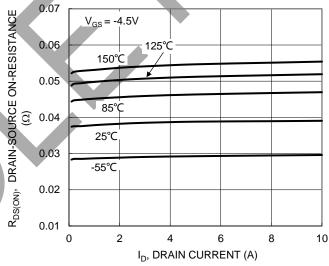


Figure 4. Typical On-Resistance vs. Drain Current and Junction Temperature

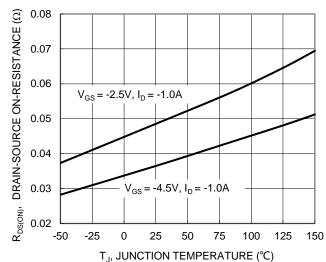


Figure 6. On-Resistance Variation with Junction Temperature



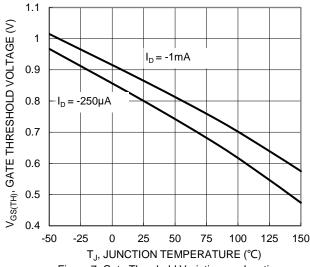
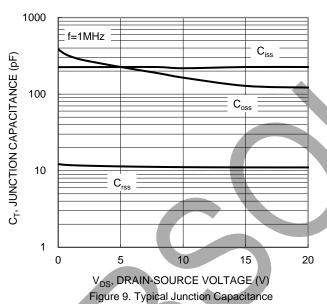


Figure 7. Gate Threshold Variation vs. Junction Temperature



P_W =1ms $P_{W} =10ms$ $P_{W} =10ms$ $P_{W} =100ms$ $T_{J(Max)} = 150^{\circ}C$ $T_{C} = 25^{\circ}C$ Single Pulse $DUT on 1^{\circ}MRP Board$ DC

V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 11. SOA, Safe Operation Area

10

=100µs

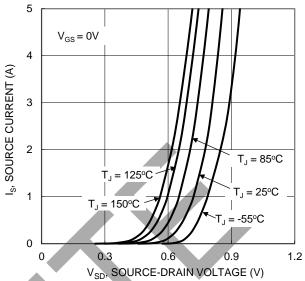


Figure 8. Diode Forward Voltage vs. Current

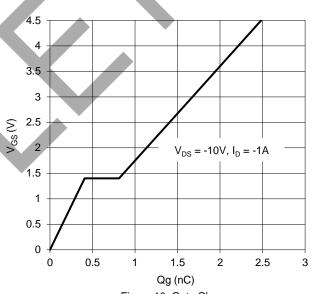


Figure 10. Gate Charge

 $V_{GS} = -4.5V$

100

10

0.01 - 0.1

 $R_{DS(ON)}$ Limited

100



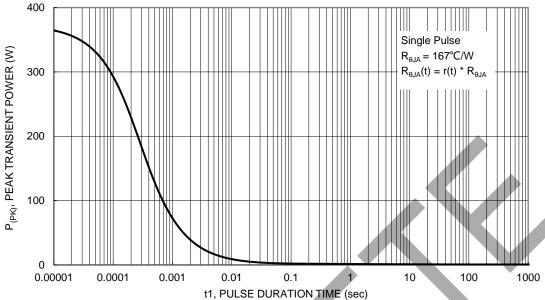


Figure 12. Single Pulse Maximum Power Dissipation

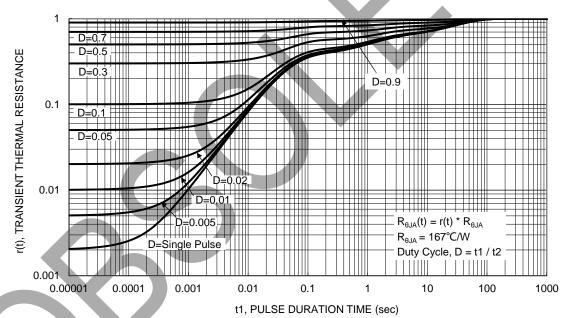


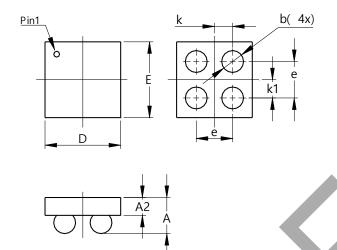
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-WLB1010-4 (Type C)

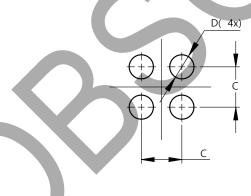


U-WLB1010-4									
	(Type C)								
Dim	Min	Max	Тур						
Α	40	0.62							
A2	-	-	0.38						
b	0.25	0.35	0.30						
۵	0.92	1.00	0.96						
E	0.92	1.00	0.96						
е	-		0.50						
k	-		0.25						
k1		-	0.25						
All Dimensions in mm									

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-WLB1010-4 (Type C)



Dimensions	Value (in mm)
С	0.500
D	0.300



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